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Date: Jul 19, 2019

2ADEPCMUE5-B PartsLst1.pdf

Run Description: Item Number: CMU-E5S, Item Name: Edge E5S Asset Monitoring Device, Revision: D

| lovol | item number | item name | revision | description | quantity | unit of | line number | reference_designator | bom notes |
|---------|-------------|--|----------------|--|----------|---------|----------------|---------------------------------------|---------------|
| | CMU-E5S | Edge E5S Asset Monitoring Device | D | Edge E5S Asset Monitoring Device | | EA | Humber | reference_designator | DOIT_HOLES |
| 1 | | Enclosure lid, CMU, E Series - S Case | G | Enclosure lid, CMU, E Series - S Case | | EA | | | IS Part |
| 1 | | Box, Edge S Series, Outer Carton | D | Box, Edge S Series, Outer Carton (10 Pack) | | | 16 | | |
| | 210101 | Box, Lugo o conso, cutor curton | | Less, Lage & Contoo, Gater Carter (10 1 dok) | 0.1 | | | | |
| 1 | 213465 | Box, Edge T4S / T5S, Large Partition | Α | Box, Edge T4S / T5S, Large Partition | 0.1 | EA | 17 | | |
| 1 | 213466 | Box, Edge T4S / T5S, Pad | Α | Box, Edge T4S / T5S, Pad | 0.1 | EA | 18 | | |
| 1 | 213467 | Box, Edge T4S / T5S, Small Partition | Α | Box, Edge T4S / T5S, Small Partition | 0.4 | EA | 19 | | |
| 1 | 213622 | Silicone Foam Pad, .75" x .75"x.032" Thk w/ | С | Silicone Foam Pad, .75" x .75"x.032" Thk w/ | 2 | EA | 12 | | |
| | | PSA backing | | PSA backing Continuous operating | | | | | |
| | | | | temperature range -40C to 105C (min.) | | | | | |
| 1 | | Silicone Foam Pad, .75" x .75"x.063" Thk w/ | В | Silicone Foam Pad, .75" x .75"x.063" Thk w/ | 4 | EA | 5 | | |
| | | PSA backing | | PSA backing Continuous operating | | | | | |
| | | | | temperature range -40C to 105C (min.) | | | 1 | | |
| 1 | | Label, IS, substitution warning | C | Label, IS, substitution warning | | EA | 20 | | IS Part |
| 1 | | Label, AAR compliance, yellow | E | Label, AAR compliance, yellow | | EA | 10 | | |
| 1 | 300842 | Screw, Plastite 48-2, 8-16 x .75, Pan Head, Torx, 18-8 SS | l _B | Screw, Plastite 48-2, 8-16 x .75, Pan Head, Torx, 18-8 SS | 4 | EA | 9 | | |
| <u></u> | 204200 | Label, blank, 2"x1", White, Thermal transfer | ^ | Label, blank, 2"x1", White, Thermal transfer | 4 | EA | 23 | | IS Part |
| ' | 301209 | imprintable polyester | l ^A | imprintable polyester with extra aggressive 2 | | EA | 23 | | S Part |
| | | Imprintable polyester | | mil Heavy Coat Weight (HCW) acrylic | | | | | |
| | | | | adhesive. UL file MH16411. Maximum | | | | | |
| | | | | operating temperature 100C. | | | | | |
| | | | | | | | | | |
| 1 | 303382 | Battery Pack, LiSOCL2, 7.2V 19AHr, IS, | G | Battery Pack, LiSOCL2, 7.2V 19AHr, IS, | 1 | EA | 7 | | IS Part |
| | | Ed6 | | Ed6 (2 D-Cells) | | | | | |
| 2 | 303375 | PCBA, Battery Board Ed6 | D | PCBA, Battery Board Ed6 | 1 | EA | 1 | | IS part |
| 3 | 300753 | Res, thick film, 0.33 ohm, 1W, 1%, 1210 | Α | | | EA | | R1,R2,R3,R4,R5,R6,R7,R8 | IS PART |
| 3 | 303374 | FAB, Battery Board Ed6 | C3 | Fabrication Files for the Battery Board | 1 | EA | | | IS PART |
| | | | | upgrades to meet the Edition 6 standards | | | | | |
| 3 | | | В | FUSE BOARD MNT 630MA 125VAC/VDC | 1 | EA | | F1 | IS PART |
| 3 | 303524 | DIODE SCHOTTKY 40V 2A SMA | Α | 3A parts acceptable | 12 | EA | | D1,D2,D3,D4,D5,D6,D7,D8,D9,D10,D11,D1 | IS PART |
| | 740,00044 | In the Hole is a second | | I I I I I I I I I I I I I I I I I I I | | | | 2 | |
| | 740-00014 | IS and RoHS Requirements | G | IS and RoHS Requirements | | EA | | | IO DOOLINGNIT |
| 3 | 780-00034 | SCH, Battery Board, Ed6 | C5 | Schematic for the Battery Board to meet Edition 6 of IEC 60079-11 Standard | | EA | | | IS DOCUMENT |
| 2 | 303376 | Cable Assembly, Battery Pack, 7.2V, E- | В | Cable Assembly, Battery Pack, 7.2V, E- | 1 | EA | 2 | | IS part |
| | | Series | | Series | | | | | |
| 3 | 300871 | Connector, Receptacle, 3mm, 2pos, Mate-n- | Α | UL File E28476 COT is -40C to 105C. | 1 | EA | 1 | | |
| | | lok | | | | | | | |

| 3 | 300872 Connector, Socket, 20-24 AWG, Gold Cr | imp A | UL File E28476 COT is -40C to 105C. | 2 EA | | |
|---|--|---------|---|--------|---------|-----------------------|
| 3 | 303546 SILICON WIRE 24AWG BLK 500' | A | 0.55mm insulation thickness, UL3239 style, REI HSING WIRE CO LTD UL file E108485, Continuous operating temperature -50C to 150C. | 100 EA | | EA = mm IS Part |
| 3 | 303547 SILICON WIRE 24AWG RED 500' | A | 0.55mm insulation thickness, UL3239 style, REI HSING WIRE CO LTD UL file E108485, Continuous operating temperature -50C to 150C. | 100 EA | | EA = mm IS Part |
| 2 | 303413 ITW Formex GK Polypropylene Sheet, 0.45mm (.017") Thick, Black | В | ITW Formex GK Polypropylene Sheet, .017" Thick. UL file E121855. Maximum operating temperature 115C. | 1 AR | 5 | |
| 2 | 303420 Heat Shrink, PVC, 96mm x 6mil, Clear | В | Heat Shrink, PVC, 96mm x 6mil, Clear, UL File E129478, Continuous operating temperature -40C to 185C. | 1 AR | 8 | |
| 2 | 303546 SILICON WIRE 24AWG BLK 500' | A | 0.55mm insulation thickness, UL3239 style, REI HSING WIRE CO LTD UL file E108485, Continuous operating temperature -50C to 150C. | 1 EA | 6 | IS part |
| 2 | 303547 SILICON WIRE 24AWG RED 500' | A | 0.55mm insulation thickness, UL3239 style, REI HSING WIRE CO LTD UL file E108485, Continuous operating temperature -50C to 150C. | 1 EA | 7 | IS part |
| 2 | 303553 Epoxy, Potting Compound, EP1282 Clear part, 50ml Tubes | -, 2- A | Epoxy, Potting Compound, EP1282 Clear, 2-part, 50ml Tubes UL File E186034. Continuous Operating Temperature -40C to 140C. 1.5mm thickness, HB rated, RTI for mechanical impact is 90C | 1 ML | 3 | IS part |
| 2 | 303583 Heatshrink, 1/8", 1/16"R, Black, LSZH Polyolefin | A | Heatshrink, 3.2mm (1/8"), 1.6mm (1/16"R), Black, LSZH Polyolefin, UL file E38155. Continuous operating temperature -40C to 125C. | 1 FT | 0 | |
| 2 | 303602 Label, blank, 2"x2", White, Thermal trans imprintable polyester | fer A | Label, blank, 50.8mm X 50.8mm [2"x2"], White, Thermal transfer imprintable polyester with extra aggressive 2 mil Heavy Coat Weight (HCW) acrylic adhesive. UL file MH16411. Maximum operating temperature 100C. | 1 EA | 10 | |
| 2 | 303623 Battery, Li-SOCl2, 3.6V, 19Ah, D-cell | А | | 2 EA | 4 | IS part |
| 2 | 303665 Miscellaneous Packaging Materials for Cl Battery Assemblies | MU A | As required adhesive and insulating materials suitable for use in battery packs 303382 and 303406 | 1 EA | 14 | As Required |
| 3 | 303656 Heat Shrink, Polyolefin, 3.18mm (0.125") Black | , В | Heat Shrink, Polyolefin, 3.18mm (0.125"), Black, UL File E38155, Continuous operating temperature -55C to 125C. | 1 AR | SHRINK1 | For battery terminals |
| 3 | 303657 Tape, Kapton polyamide film, 19.1mmW (3/4"W), Amber | A | Tape, Kapton polyamide, 19.1mm W (3/4"W), Amber, UL file E124809, Continuous operating temperature -73 to 260C | 1 AR | TAPE2 | Potting dam |

| | Tape, Acrylic adhesive transfer tape 9082, Clear | a N | ape, Ultra High Temperature Acrylic dhesive transfer tape 9082, Clear, UL file IH17478, Maximum operating temperature 20C | 1 | AR | Tape1 | As required. For positioning parts before potting |
|--|--|-------------|---|---|----|--------------------|---|
| 2 740-00018 | E Series Battery Pack Serialization | | rawing defining the requirements for serial umbers for E series battery packs | 1 | EA | 0 N/A | Serial number includes supplier number an code for battery manufacturer |
| 1 303417 | Enclosure Base, CMU, E Series - S case | D E | nclosure Base, CMU, E Series - S case | 1 | EA | 1 | IS Part |
| | Screw, Plastite 48-2, 6-19 x .38, Pan Head, Torx, 18-8 SS | I I | crew, Plastite 48-2, 6-19 x .38, Pan Head, orx, 18-8 SS | 6 | EA | 8 | |
| 1 303456 | Label, IS-Warning, E Series, French | C L | abel, IS-Warning, E Series, French | 1 | EA | 24 | IS Part |
| 1 303457 | Label, IS, Substitution Warning, French | B L | abel, IS, Substitution Warning, French | 1 | EA | 20 | IS Part |
| 1 303458 | Label, IS, E-Series | E L | abel, IS, E-Series | 1 | EA | 11 | IS Part |
| 1 303493 | Imprint Spec, Label, Serial Number | B In | nprint Spec, Label, Serial Number | 1 | EA | 22 | IS Part |
| 1 303550 | Intrinsic Safety Manual E-series CMU | | ntrinsic Safety Manual, E4S, E5S, E4X, 5X, E6S | 1 | EA | 27 | IS Part User Manual One copy with each shipment |
| 1 303551 | Label, IS-Warning, E Series | C L | abel, IS-Warning, E Series | 1 | EA | 21 | IS Part |
| | O-Ring, 3/32 Thk x 6-1/2 ID, 30 Durometer, Silicone | | P-Ring, 3/32 Thk x 6-1/2 ID, 30 Durometer, ilicone | 1 | EA | 3 | IS Part |
| | Breather, GoreTex, 14mm dia, self adhesive, Black | a | reather, GoreTex, 14mm dia, self dhesive. Continuous operating emperature -40C to 100C. UL file E332853. | 1 | EA | 4 | IS Part |
| 1 740-00014 | IS and RoHS Requirements | G IS | S and RoHS Requirements | 0 | EA | 100 | IS Part all manufacturers of system shall read document prior to assembly. |
| 1 XX = 05 Option | PCBA, EMU, XX = 05 Option | c | his is the PCBA for the Primary Cell Phone communication Type, with the Smart Mesh internet Protocol Manager Option Installed. | 1 | EA | 6 | IS Part |
| | PCBA, EMU, E5 4G/2G GG0 NA Configuration | P A G | his is the PCBA for the E-series CMU-E5, rimary Cell Phone, SMIP Manager, North merican SIM, 2G/4G Cell Modem, Giant Gecko Rev 0, and External memory opulated. | 1 | EA | | E-series CMU-E5, Primary Cell Phone, SMIP Manager, North America SIM, 2G/4G Cell Modem, Giant Gecko Rev 0, and External memory populated |
| 3 PCBAC3-XX-UU-T-P-M | PCBA, CMU3, Main Board w/ options | A | CBA, CMU, Main Board w/ options XX is ux Comm UU is SIM card Installation T- ell modem chip P - processor M - memory | 1 | EA | | PCBA to be assembled per options defined in Item part number |
| 4 128M Flash Option U210 or U211 - NOT Both | IC FLASH 128M 133 MHz | | tuff either U210 or U211. Other part is IOPOP. | 1 | EA | 67 | Two footprints - only one gets stuffed |
| 4 300291 | Sealant, Silicone-Fast Tack 3165 Grey | | old P/N 415-00002, Continuous operating emperature -45C to 200C. UL File E40195. | 1 | AR | 40 RTV | Seal around and over C611 and L720 to trap air inside part. |
| 4 300795 | Cap, MLC, 1uF, 16V, X7R, 0805, +/-10% | D | | 2 | EA | 6 C701, C725 | |
| | | D | | | EA | 7 C342, C700, C724 | |
| | | В | | | EA | 33 D720 | |
| 4 300816 | Inductor, 4.7uH, 5.6A, 20%, 10.2x10.2x4.5mm | C m | netal composite, shielded | | EA | 59 L720 | |

| г . г | | | . 1 | | ala | 1 |
|-------|---|---|-------|-------|---|---|
| 4 | 300884 Cable Assembly, Power, 3.2A, 250V | Cable Assembly, Power, 3.2A, 250V Red wire Alpha Wire 6712 UL Style 11028, UL File E163869, COT -40C to 105C. 2. Black wire Alpha Wire 6712 UL Style 11028, UL File E163869, COT -40C to 105C Connector housing TE connectivity P/N 1445049-2 UL File E28476 COT is -40C to 105C. Connector contact TE connectivity P/N 1-794612-2 UL File E28476 COT is -40C to 105C | 1 | EA | 5 CA1 | Attach to P70, RED 1, BLK 2 |
| 4 | 301159 CAP CER 47PF 50V 5% NP0 0402 B | | 21 | EA | 25 C220, C223, C229, C600, C601, C605, C606, C616, C631, C632, C633, C641, C707, C709, C710, C732, C734, C783, C785, C789, C791 | |
| 4 | 301200 Loctite 401 Cyanoacrylate Adhesive, .7oz (20g) bottle, Clear | 401 PRISM is a low viscosity, fast curing, single component cyanoacrylate adhesive. It is specifically formulated for difficult to bond substrates and is less dependent on surface moisture for cure speed than other standard CA grades. 20 gram bottle. Continuous operating temperature -40 to 85C. | 0.001 | AR | 0 | 2 drops for NFC antenna |
| 4 | 301487 CAP CER 0.1UF 50V 10% X7R 0402 C | CAP CER 0.1UF 50V 10% X7R 0402 | 43 | EA | 10 C103, C104, C105, C106, C107, C108, C117, C118, C130, C201, C203, C216, C221, C249, C302, C304, C321, C322, C330, C331, C343, C345, C347, C400, C402, C410, C412, C421, C422, C453, C630, C640, C690, C691, C706, C708, C722, C723, C731, C733, C784, C788, C790 | NOPOP C211 |
| 4 | 301523 IC ACCEL 8G DIG LO PWR 3AX 16LGA B | IC ACCEL 8G DIG LO PWR 3AX 16LGA | 1 | EA | 46 U400 | |
| 4 | 301537 Tape, VHB 4905 Clear, 3/4 in x 72 yd 20.0 A mil | 3M VHB Tape 4905 Clear, 3/4 in x 72 yd 20.0 mil | 1.25 | IN | 43 | Apply 1.25" tape to separate C780-C782 from modem U600, before applying low pressure mold |
| 4 | 301759 FUSE BOARD MNT 125MA 125VAC/VDC A | FUSE BOARD MNT 125MA 125VAC/VDC | 1 | EA | 41 F70 | IS PART |
| 4 | 301762 IC ACCEL 200G DIG LO PWR 3AX 16LGA | IC ACCEL 200G DIG LO PWR 3AX 16LGA | 1 | EA | 47 U410 | |
| 4 | 301765 FILTER CHIP 1000 OHM 250MA 0402 B | FILTER CHIP 1000 OHM at 100MHz 250MA 0402 | 22 | EA | 62 FB94, FB95, FB96, FB97, FB98, FB99, FB119, FB120, FB420, FB801, FB802, FB803, FB804, FB805, FB806, FB807, FB808, FB809, FB810, FB811, R401, R410 | |
| 4 | 301775 RES SMD 1K OHM 1% 1/10W 0402 B | RES SMD 1K OHM 1% 1/10W 0402 | 3 | EA | 80 R130, R199, R431 | |
| 4 | 301778 RES SMD 18.7K OHM 1% 1/10W 0402 B | RES SMD 18.7K OHM 1% 1/10W 0402 | | EA | 82 R721 | |
| 4 | 301781 RES SMD 63.4K OHM 1% 1/10W 0402 B | RES SMD 63.4K OHM 1% 1/10W 0402 | | EA | 84 R720, R723 | |
| 4 | 301782 RES SMD 845K OHM 1% 1/16W 0402 B | RES SMD 845K OHM 1% 1/16W 0402 | 1 | EA | 85 R722 | |
| 4 | 301783 CAP CER 22PF 50V 5% NP0 0402 B | CAP CER 22PF 50V 5% NP0 0402 | 2 | EA | 14 C222, C726 | |
| · | 001700 0711 0E17 2E11 00 0 070 111 0 0+02 | | | | ·-la a | |
| 4 | 301785 CAP CER 68PF 50V 5% NP0 0402 B | CAP CER 68PF 50V 5% NP0 0402 | 3 | EA | 15 C70, C703, C729 | |
| 4 4 | | CAP CER 68PF 50V 5% NP0 0402 CAP CER 6.2PF +/-0.25pF 50V NP0 0402 | | EA EA | 15 C70, C703, C729 16 C307, C308, C608, C615 | |
| 4 | 301785 CAP CER 68PF 50V 5% NP0 0402 B | CAP CER 6.2PF +/-0.25pF 50V NP0 0402 | 4 | | | |
| 4 4 | 301785 CAP CER 68PF 50V 5% NP0 0402 B 301788 CAP CER 6.2PF +/-0.25pF 50V NP0 0402 B | CAP CER 6.2PF +/-0.25pF 50V NP0 0402 CAP CER 100UF 10V 20% X5R 1210 | 7 | EA | 16 C307, C308, C608, C615 | |

| | 301797 IC REG LDO 1.8V 0.15A TSOT23-5 | В | IC REG LDO 1.8V 0.15A TSOT23-5 | 1 EA | 48 U341 | T |
|---|---|----------------|---|---------|--|--|
| 4 | 301797 IC REG EDO 1.6V 0.15A 150123-5 301801 IC NFC/RFID TAG 64KB EEPROM 8SOI | В | IC NFC/RFID TAG 64KB EEPROM 8SOI | 1 EA | 50 U220 | |
| 4 | 301809 IC BUS TRANSCVR 4BIT 16-UQFN | B | IC BUS TRANSCVR 4BIT 16-UQFN | 4 EA | 53 U321, U331, U652, U691 | |
| 4 | | В | · | | | <u> </u> |
| 4 | 301812 IC LOAD SWITCH LV DUAL SOT23-8 | A | IC LOAD SWITCH LV DUAL SOT23-8 | 2 EA | 54 U240, U450 | |
| 4 | 301813 IC SWITCH SPDT SC70-6 | C | IC SWITCH SPDT SC70-6 | 1 EA | 55 U721 | |
| 4 | 301832 Supercap, 120mF, 20%, 5.5V | A | ESR = 140 mOhm 20x18x3mm -40 to +85C | 1 EA | 21 C611 | |
| 4 | 301837 RES SMD 226K OHM 1% 1/10W 0402 | D | RES SMD 226K OHM 1% 1/10W 0402 | 1 EA | 87 R725 | |
| 4 | 301838 CAP CER 0.22UF 10% 10V X7R 0402 | Ь | CAP CER 0.22UF 10% 10V X7R 0402 | 1 EA | 12 C424 | |
| 4 | 303335 0805 PROBE PAD | D A | SMD 0805 TEST PROBE PAD | 8 EA | 69 TP101, TP240, TP340, TP445, TP450, | <u> </u> |
| 4 | 303335 0605 PROBE PAD | l ^A | SIND 0803 TEST PROBE PAD | O EA | TP520, TP606, TP700 | |
| 4 | 303346 CONN UMC JACK STR 50 OHM SMD | А | CONN UMC JACK STR 50 OHM SMD | 0 EA | 31 | J620 - Only installed for design qualification testing. |
| 4 | 303351 CAP CER 22UF 10V 20% X5R 0805 | C | CAP CER 22UF 10V 20% X5R 0805 | 2 EA | 24 C401, C411 | loosiing. |
| 4 | 303371 Technomelt PA 678 Thermoplastic | C | Technomelt PA 678 Thermoplastic | 0.25 LB | 70 | Material Used for encapsulating Electronics |
| | Polyamide | | Polyamide, UL file E182771, Continuous operating temperature -40C to 140C. | 0.20 EB | | IS PART |
| 4 | 303389 Antennas LTE 700-LTE 2400MHz Max RL - 6dB | А | Antennas LTE 700-LTE 2400MHz Max RL - 6dB, Continuous operating temperature - 40C to 125C | 1 EA | 3 A620 | |
| 4 | 303390 CAP CER 0.5PF +/-0.05pF 50V NP0 0402 | В | CAP CER 0.5PF +/-0.05pF 50V NP0 0402 | 1 EA | 26 C622 | |
| 4 | 303391 RES SMD 100 OHM 1% 1/10W 0603 | С | RES SMD 100 OHM 1% 1/10W 0603 | 3 EA | 88 R605, R784, R789 | |
| 4 | 303392 CAP CER 2.2PF 50V NP0 0402 | В | CAP CER 2.2PF 50V NP0 0402 | 1 EA | 27 R624 | |
| 4 | 303393 FIXED IND 3.3NH 300MA 190 MOHM | A | FIXED IND 3.3NH 300MA 190 MOHM | 1 EA | 60 C623 | |
| 4 | 303394 FIXED IND 15NH 5% 300MA 460 MOHM | Δ | FIXED IND 15NH 5% 300MA 460 MOHM | 1 EA | 65 L620 | L623 NOPOP |
| 4 | 303395 RF Shield, E-Series CMU Board | G | RF Shield, E-Series CMU Board 0.3mm Thick Nickel Silver 770 Half Hard | 0 EA | 38 | NOPOP SHLD700 |
| 4 | 303397 CAP CER 12PF 5% 50V NP0 0402 | В | CAP CER 12PF 5% 50V NP0 0402 | 2 EA | 28 C613, C614 | |
| 4 | 303483 Solid Silicone Pad, .75" x .75"x.031" Thk, Red,, 30 Durometer w/ PSA backing | A | Solid Silicone Pad, .75" x .75"x.031" Thk, Red, 30 Durometer w/ PSA backing, Continuous operating temperature range - 40C to 105C (min.) | 1 EA | 42 | Place Pad over C611 to protect from high temperature molding process |
| 4 | 303508 CAP CER 2.2UF 10% 10V X6S 0402 | В | CAP CER 2.2UF 10% 10V X6S 0402 | 24 EA | 11 C97, C98, C99, C100, C101, C102, C119, C120, C121, C202, C204, C212, C213, C244, C248, C301, C303, C323, C344, C423, C452, C602, C607, C642 | |
| 4 | 303512 CAP CER 0.022UF 10% 35V X7R 0402 | А | CAP CER 0.022UF 10% 35V X7R 0402 | 1 EA | 95 C702 | |
| 4 | 303513 FERRITE BEAD 26 OHM 0603 | A | FERRITE BEAD 26 OHM 0603 | 2 EA | 96 L721, L722 | |
| 4 | 303525 Res, thick film, 0 ohm, 1/16W, 1%, 0402 | A | 0 ohm 0402 | 4 EA | 75 R342, R343, R344, R705 | |
| 4 | 303526 IC, switching regulator, buck-boost, LTC3112, TSSOP-20 | A | LTC3112, TSSOP-20 | 1 EA | 44 U720 | |
| 4 | 303530 FERRITE BEAD 220 OHM at 100 MHz 0603 | A | FERRITE BEAD 220 OHM at 100 MHz 0603 | 3 EA | 64 l80, L601, L602 | |
| 4 | 303531 Oscillator, 32.768KHz, 3.3V | В | '-40 to +85C | 1 EA | 71 X130 | |
| 4 | 303534 RES 100K OHM 1/16W 1% 0402 SMD | Α | RES 100K OHM 1/16W 1% 0402 SMD | 4 EA | 77 R210, R211, R660, R663 | |
| 4 | 303535 RES 1K OHM 1/10W 1% 0603 SMD | Α | RES 1K OHM 1/10W 1% 0603 SMD | 9 EA | 78 R320, R640, R654, R655, R656, R657, | IS PART |
| | AUTOMOTIVE | | AUTOMOTIVE | | R692, R693, R694 | |
| 4 | 303536 RES SMD 10K OHM 1% 1/10W 0402 | А | RES SMD 10K OHM 1% 1/10W 0402 | 7 EA | 81 R224, R225, R308, R422, R423, R645, R704 | |
| 4 | 303537 RES SMD 274K OHM 1% 1/10W 0402 | Α | RES SMD 274K OHM 1% 1/10W 0402 | 2 EA | 83 R703, R724 | |
| | <u>_</u> | | | | <u> </u> | 1 |

| 4 | 303538 | RES 1.2M OHM 1% 1/10W 0402 | A | RES 1.2M OHM 1% 1/10W 0402 | 16 EA | 86 R430, R601, R602, R603, R604, R701, R780, R781, R782, R783, R785, R786, R787, R788, R790, R791 | |
|---|--------|--|---|--|-------|--|---|
| 4 | 303540 | Switch, Reed, 0.5A, 10-15 AT, SMT | В | | 1 EA | 92 S430 | |
| 4 | | TRANS 2NPN 65V 0.1A SOT363 | A | TRANS 2NPN 65V 0.1A SOT363 | 1 EA | 93 T660 | |
| 4 | | IC OPAMP GP 3KHZ RToR TSOT23-5 | A | '-40 to 125C | 3 EA | 45 U601, U780, U781 | |
| 4 | | IC REG BUCK ADJ 0.3A SYNC 10MSOP | A | IC REG BUCK ADJ 0.3A SYNC 10MSOP | 1 EA | 49 U700 | |
| 4 | | Res, thick film, 10.0K, 1/10W, 1%, 0603 | A | | 20 EA | 74 R321, R322, R323, R324, R325, R326, R327, R329, R331, R332, R661, R662, R717, R718, R727, R728, R729, R730, R731, R732 | IS PART |
| 4 | 303557 | RES 35.7 Ohm 1% 2W 2512 | A | RES 35.7 Ohm or 36 Ohm 1% 2W 2512 | 2 EA | 76 R70, R71 | IS PART |
| 4 | 303565 | Diode, Schottky, 40V, 3A, SMB | В | Diode, Schottky, 40V, 3A, SMB | 4 EA | 32 D70, D71, D72, D73 | IS PART |
| 4 | | Wire, 26AWG, 7/34, 150V, IR XLPVC, White, 1000 FT | A | 0.25mm insulation thickness, UL1429 style, Alpha Wire UL file E163869, CSA AWM I A/B FT1, Continuous operating temperature 55C to 80C | 1 ROL | 4 Cable1 | Two 4.75 inch length wires, +/- 0.25 inch, strip per antenna A220 |
| 4 | 303617 | RF ANTENNA GPS/Glonass, Patch, 18x18x4mm | A | RF ANTENNA 1.56-1.61GHz, Patch, 18x18x4mm, Continuous operating temperature is -40C to 85C. | 1 EA | 1 A300 | |
| 4 | 303621 | CAP CER 10UF 10V 10% X5R 0805 AUTOMOTIVE | В | CAP CER 10UF 10V 10% X5R 0805 AUTOMOTIVE | 1 EA | 13 C705 | |
| 4 | 303632 | FAB, CMU3 board | С | Fabrication files for the CMU3 Main circuit board with LTE-2G Cellular modem | 1 EA | 72 FAB | IS PART |
| 4 | 303637 | IC MAGNETOMETER IIS2MDC XYZ DIGITAL 12DFN | A | IC MAGNETOMETER XYZ DIGITAL 12DFN | 0 EA | 51 | NOPOP U420 |
| 4 | 303638 | MOSFET N-CH 50V 0.2A SOT-23 | A | MOSFET N-CH 50V 0.2A SOT-23 Thermal resistance 380 C/W | 1 EA | 94 Q702 | |
| 4 | 303639 | MOSFET P-CH 20V 8A 8-SOIC | A | MOSFET P-CH 20V 8A 8-SOIC. Thermal resistance with copper under part is 105 C/W | 1 EA | 98 Q701 | |
| 4 | 303640 | CAP FEEDTHRU 0.01UF 100V 1206 | A | CAP FEEDTHRU 0.01UF 100V 1206 | 1 EA | 61 EMI1 | |
| 4 | 303642 | IND 10UH 20% 700MA 380 MOHM 1210 | A | Shielded Inductor for Power Line | 1 EA | 63 L700 | |
| 4 | 303671 | MOD RX SE873Q5 GNSS 24LCC | A | MOD RX SE873Q5 GNSS 24LCC | 1 EA | 57 U302 | |
| 4 | 303672 | DIODE ZENER 6.2V 5% 200MW SMINI2 | A | DIODE ZENER 6.2V 5% 200MW SMINI2 | 18 EA | 34 D303, D304, D305, D306, D307, D308, D309, D310, D311, D312, D717, D718, D727, D728, D729, D730, D731, D732 | IS PART |
| 4 | 303677 | DIODE ZENER 6.2V 5% 5W DO214AA(SMB) | A | DIODE ZENER 6.2V 5W 5% DO214AA(SMB) | 6 EA | 36 D301, D302, D701, D702, D721, D722 | IS PART |
| 4 | 303689 | CAP CER 0.01uF 500V 20% X7R 0805 | A | CAP CER 0.01UF 500V 20% X7R 0805, -55 to 125C, 1.4mm thick | 4 EA | 9 C225, C226, C227, C228 | IS PART |
| 4 | 303690 | CAP CER 47PF 10% 500V X8G 0603 Hi-Q | В | 47pF ±10% 500V Ceramic Capacitor X8G 0603 (1608 Metric) High Reliability | 4 EA | 23 C305, C306, C620, C621 | IS PART C625 only installed for Design qualification |
| 4 | 303691 | Supercap, 10F-12F, 2.7V, 10x30mm, radial, -20/+10% | A | DCRmax <= 85mohm ACRmax <= 60mohm lleak <= 30uA lcont(max) >= 3.5A lpeak(max) >= 7.7A Temp = -40 to 70C | 3 EA | 8 C780, C781, C782 | |
| 4 | 303725 | FIXED IND 13nH 3% 400mA 260 mOHM | A | FIXED IND 13nH 3% 400mA 260 mOHM | 1 EA | 66 L621 | |
| 4 | | NFC STAMP FLEX ANTENNA 55X45MM | Ā | NFC STAMP FLEX ANTENNA 55X45MM, without ferrite, Continuous operating temperature is -30C to 85C. 13.56 MHz, 2.59 uH, 0.17mm thick | 1 EA | 2 A220 | Attach with Cable1 |

| 4 4G_AUX_COMM_MODULE-XX | 4G Auxiliary Communications module for the EMU | A | Auxiliary Communications module for the EMU 04=Primary Cell Phone 05=Primary Cell Phone and Local WSN Manager 06=Primary Cell Phone, Local WSN Manager and Intra-Train Network 07=Primary Cell Phone, Local WSN Manager and Bluetooth Module 08=Primary Cell Phone, Local WSN Manager and WIFI Module 09=Primary Cell Phone, Local WSN Manager and Satellite Module | 1 | EA | 91 | IS PART - T5 components soldered to board, other configurations soldered to header AUX1 |
|-------------------------------|---|---------|---|----|----|--|---|
| 5 05_4G_COMM_OPTION | 05_4G_Communications_Option for E- series CMU | В | 05_4G_Communications_Option BOM structure | 1 | EA | 5 Defined_In_Sub_Circuit | IS PART |
| 6 4G_DUST_MANAGER_SUB-CIRCUIT | 4G_Dust Mesh Network Manager Sub Circuit | Α | 4G_Dust Mesh Network Manager Sub Circuit | 1 | EA | Defined_In_SubCircuit | IS PART |
| 7 30148 | 37 CAP CER 0.1UF 50V 10% X7R 0402 | С | CAP CER 0.1UF 50V 10% X7R 0402 | 2 | EA | C513, C514 | |
| | 61 Crystal 32.7680kHz 20ppm 12.5pF 90 kOhm -40°C - 85°C Surface Mount 2-SMD | A | Crystal 32.7680kHz 20ppm 12.5pF 90 kOhm -40°C - 85°C Surface Mount 2-SMD | | EA | X530 | |
| 7 30176 | 55 FILTER CHIP 1000 OHM 250MA 0402 | В | FILTER CHIP 1000 OHM at 100MHz 250MA 0402 | 6 | EA | FB550, FB551, FB552, FB553, FB554, FB555 | |
| 7 30177 | 72 Crystal 20.0000MHz 10ppm 10pF 50 Ohm - 60°C - 105°C Surface Mount HC49/US | А | Crystal 20.0000MHz 10ppm 10pF 50 Ohm - 60°C - 105°C Surface Mount HC49/US | 1 | EA | X520 | |
| 7 30177 | 75 RES SMD 1K OHM 1% 1/10W 0402 | В | RES SMD 1K OHM 1% 1/10W 0402 | 2 | EA | R502, R503 | |
| 7 30178 | 31 RES SMD 63.4K OHM 1% 1/10W 0402 | В | RES SMD 63.4K OHM 1% 1/10W 0402 | 4 | EA | R505, R508, R509, R523 | |
| 7 30178 | 35 CAP CER 68PF 50V 5% NP0 0402 | В | CAP CER 68PF 50V 5% NP0 0402 | 1 | EA | C530 | |
| 7 30178 | 38 CAP CER 6.2PF +/-0.25pF 50V NP0 0402 | В | CAP CER 6.2PF +/-0.25pF 50V NP0 0402 | 1 | EA | C519 | |
| 7 30179 | 00 CAP CER 0.47UF 10V 10% X5R 0402 | С | CAP CER 0.47UF 10V 10% X5R 0402 | 1 | EA | C507 | |
| 7 30179 | 21 CAP CER 56nF 16V 10% X7R 0402 | В | CAP CER 56nF 16V 10% X7R 0402 | 10 | EA | C503, C504, C505, C506, C508, C509, C510, C511, C515, C516 | |
| 7 30180 | 07 SAW FILTER RF 2441.8MHZ SM3030-6 | А | SAW FILTER RF 2441.8MHZ SM3030-6 | 1 | EA | SAW580 | |
| 7 30181 | 12 IC LOAD SWITCH LV DUAL SOT23-8 | Α | IC LOAD SWITCH LV DUAL SOT23-8 | 1 | EA | U520 | |
| 7 30183 | 38 CAP CER 0.22UF 10% 10V X7R 0402 | В | CAP CER 0.22UF 10% 10V X7R 0402 | | EA | C517 | |
| 7 30350 | 08 CAP CER 2.2UF 10% 10V X6S 0402 | В | CAP CER 2.2UF 10% 10V X6S 0402 | | EA | C512, C520, C521 | |
| | Res, thick film, 0 ohm, 1/16W, 1%, 0402 | Α | 0 ohm 0402 | | EA | R506 | |
| | 39 Inductor, 2.2uH, 120mA, 0603, +/-20% | Α | Old P/N 155-00004 | | EA | L501 | |
| 7 30369 | 20 CAP CER 47PF 10% 500V X8G 0603 Hi-Q | В | 47pF ±10% 500V Ceramic Capacitor X8G 0603 (1608 Metric) High Reliability | 2 | EA | C583, C584 | IS PART |
| 7 Mgr, SmartMesh IP, DUST | Manager, SmartMesh IP, DUST, Local Sensor Manager | A | Local Sensor Manager for the EMU series product | | EA | U500 | |
| 8 30180 | OO IC SMARTMESH IP MNGR 2.4GHZ 72QFN | Α | IC SMARTMESH IP MNGR 2.4GHZ 72QFN | 1 | EA | | |
| 8 510-00037 | Firmware, SmartMesh IP, DUST LTC5800 IPM Manager w/ FUSE TABLE | 1.4.2.2 | Firmware, SmartMesh IP, DUST LTC5800 IPM Manager w/ FUSETABLE Created for the EMU project | 1 | EA | | |
| 9 510-00034 | Firmware, SmartMesh IP, DUST LTC5800 IWR Manager | 1.4.2.2 | Firmware, SmartMesh IP, DUST LTC5800 IWR Manager | 1 | EA | | |
| 9 510-00036 | FUSE_TABLE, SmartMesh IP, DUST LTC5800 IPM Manager EMU board | A | This is the FUSE TABLE for the DUST SmartMesh IP Manager on the EMU boards. This file defines the crystals and tuning for board stackup. This file may need to be created for different PCB boards. | 1 | EA | | |

| 4 CELL_MODEM-T | Cell modem, GSM, quad band, 910 family | C This is an item used as a placeholder for various 910 modem configurations offered by | 1 EA | 73 U600 | T designates what item in the sub-assembly to install. |
|----------------------------|---|--|------|---------------|---|
| 5 4_CELL_MODEM_OPTION | 4_Cell_Modem_Option for E-series CMU | A 4_Cell_Modem_Option for 2G/4G Modem place holder for BOM structure | 1 EA | U600 | 4 Option is 4G/2G cellular module |
| 6 ME910C1-WW | Cell modem, LTE-GSM, ME910C1-WW | B Cell modem, LTE-GSM, ME910C1-WW Without GNSS AT+CGMR Firmware version M0B.800003 | 1 EA | U600 | 3 Option is Universal 2/3G Chip |
| 4 Memory_8SOIC-M | Memory_RAM_8SOIC | B This is a placeholder for various RAM memory configurations. | 2 EA | 68 U201, U202 | |
| 5 1_MEMORY_OPTION | 1_Memory_Option for E-series CMU | A 1_Memory_Option place holder for BOM structure | 1 EA | | Memory Populated U201, U202 |
| 6 | 301756 IC SRAM 1MBIT 20MHZ 8SOIC | B IC SRAM 1MBIT 20MHZ 8SOIC | 2 EA | U201, U202 | Option 1 populates these parts |
| 4 Processor_100LQFP14x14-P | Processor with a 100LQFP 14x14mm package size | B This is a place holder for the possibility of changing processors out depending on required functionality. | 1 EA | 58 U101 | |
| 5 0_PROCESSOR_OPTION | 0_Processor_Option for E-series CMU | A 0_Processor_Option place holder for BOM structure | 1 EA | U101 | |
| 6 | 301773 IC MCU 32BIT 1024KB FLSH 100LQFP | A IC MCU 32BIT 1024KB FLSH 100LQFP COT -40C to 85C | 1 EA | U101 | 0 Option is for Giant Gecko Rev 0 |
| 4 SIM_CARD-UU | SIM CARD-UU for Cell Modem | C This is a placeholder for the SIM Card selection on the EMU product. | 1 EA | 90 U630 | UU in the part number defines what country code will go into the product. |
| 5 NA_SIM_OPTION | NA SIM Option for E-series CMU | B North American SIM_Option for E-series CMU | 1 EA | | U630 North America SIM |
| 6 301701-NA3 | NA3 SIM Option for E-series CMU | E North American Option, 2G-3G SIM Card, Embedded, SLM76CF5120P, 8 pin, VQFN-8-1 | 1 EA | U630 | North American SIM |

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